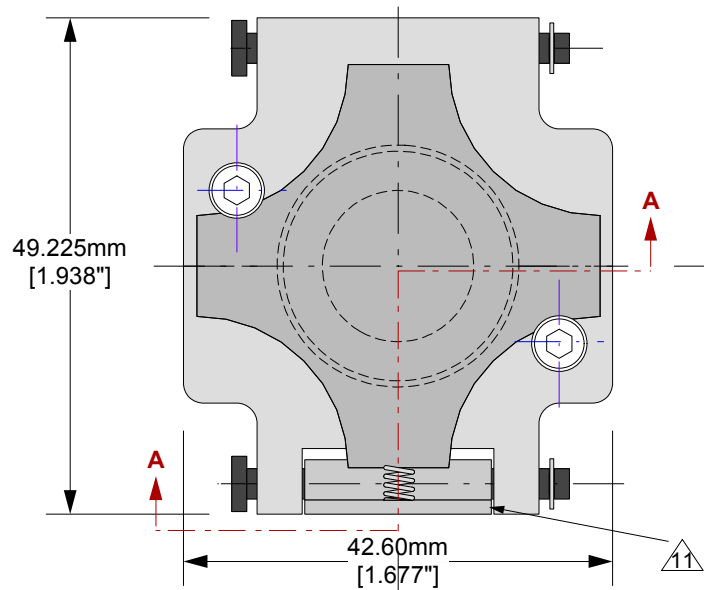
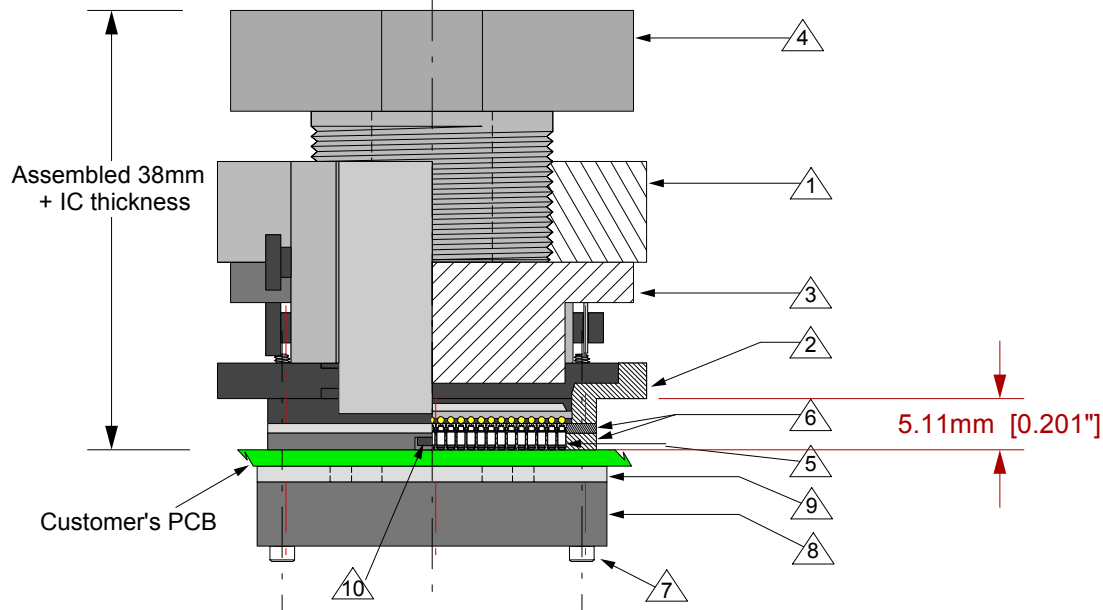


Top View



Side View  
(Section AA)



**Features**

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes evenly
- Clamshell lid

**Materials:**

- △1 Clam Shell Lid: Black anodized 7075 Aluminum. Height = 20 mm.
- △2 Socket Base: Black anodized 7075 Aluminum. Height = 6 mm.
- △3 Compression Plate: Black anodized 7075 Aluminum. Thickness = 12 mm.
- △4 Compression Screw: Clear anodized 7075 Aluminum. Height = 27 mm, Fluted Knob
- △5 Pogo Pin: Plungers - Hardened Steel/ Gold plated  
Barrel - Copper Alloy/ Gold plated  
Spring - Stainless Steel/ Gold wire
- △6 Pogo Pin Guides: Ultem 1000.
- △7 Socket Base Screw: Socket Head Cap Screw, 18-8 SS, 0-80 Thread, 3/4" long.
- △8 Backing Plate: Black anodized 7075 Aluminum
- △9 Insulation Plate: FR4/G10
- △10 Pogo Pin Guide Screw: Pan head phillips, 18-8 SS, 0-80 thread, 3/16" long.
- △11 Latch: Black anodized 7075 Aluminum.

**SS-LGA376A-01 Drawing**

Status: Released

Scale: 1.25:1

Rev: A



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Drawing: H. Hansen

Date: 2/1/06

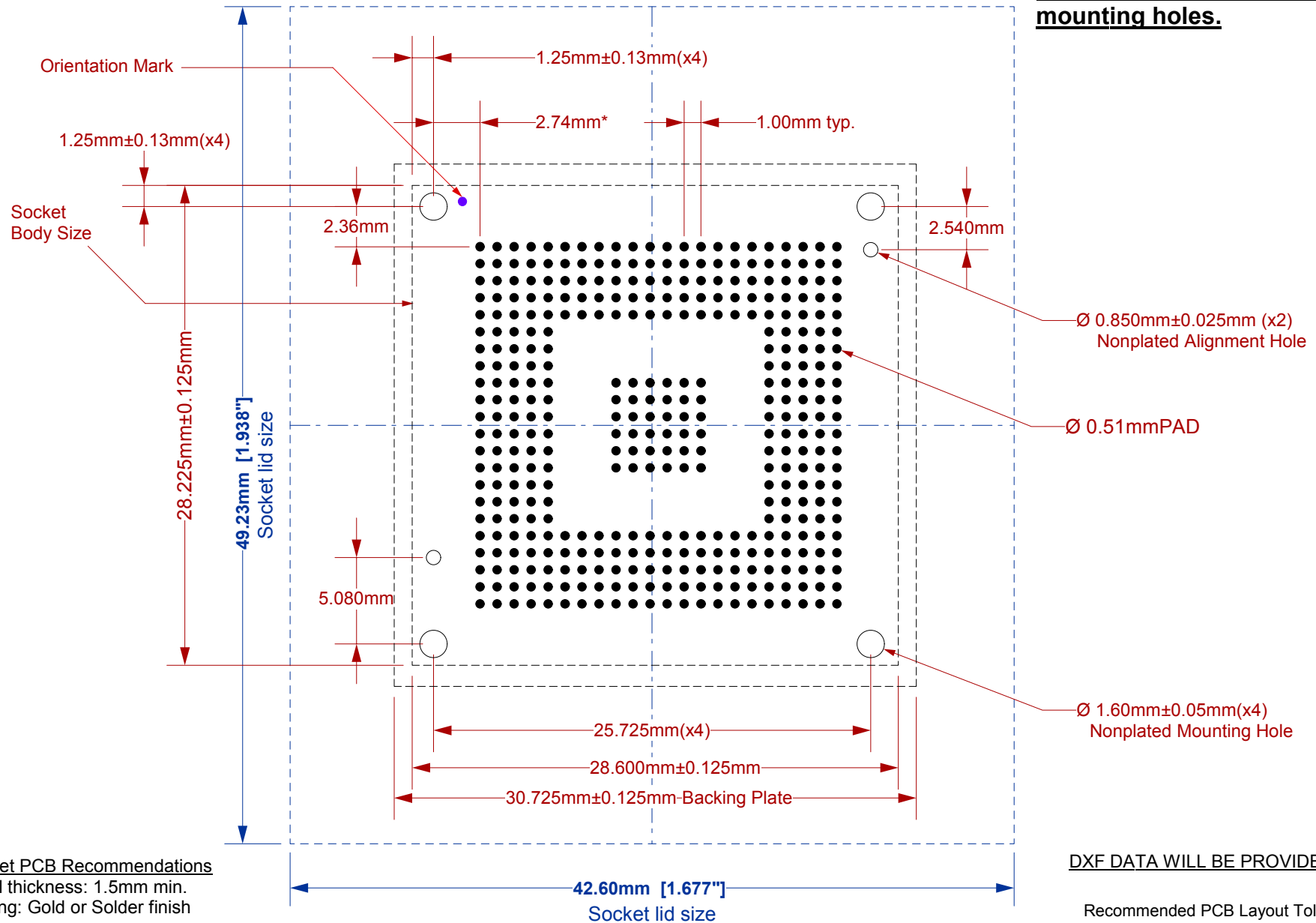
File: SS-LGA376A-01 Dwg

Modified:

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout  
Top View

**\*Note: BGA pattern is not symmetrical with respect to the mounting holes.**




Target PCB Recommendations

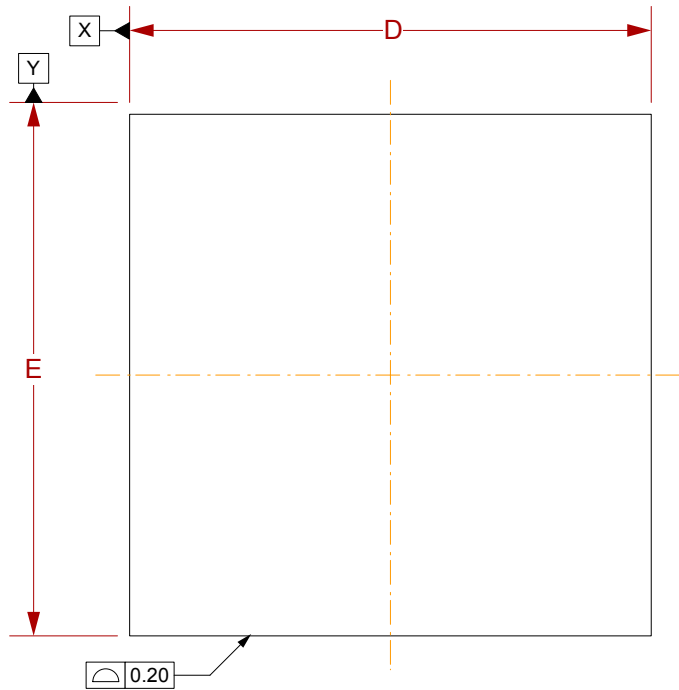
Total thickness: 1.5mm min.  
Plating: Gold or Solder finish

DXF DATA WILL BE PROVIDED

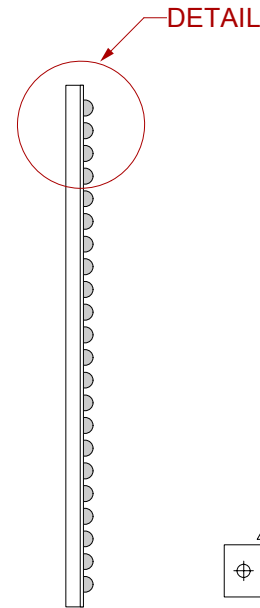
Recommended PCB Layout Tolerances:  
±0.025mm [±0.001"] unless stated otherwise.

<b>SS-LGA376A-01 Drawing</b>		Status: Released	Scale: 3:1	Rev: A
	© 2006 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com		Drawing: H. Hansen	
			Date: 2/1/06	
			File: SS-LGA376A-01 Dwg	
			Modified:	

Compatible BGA Spec

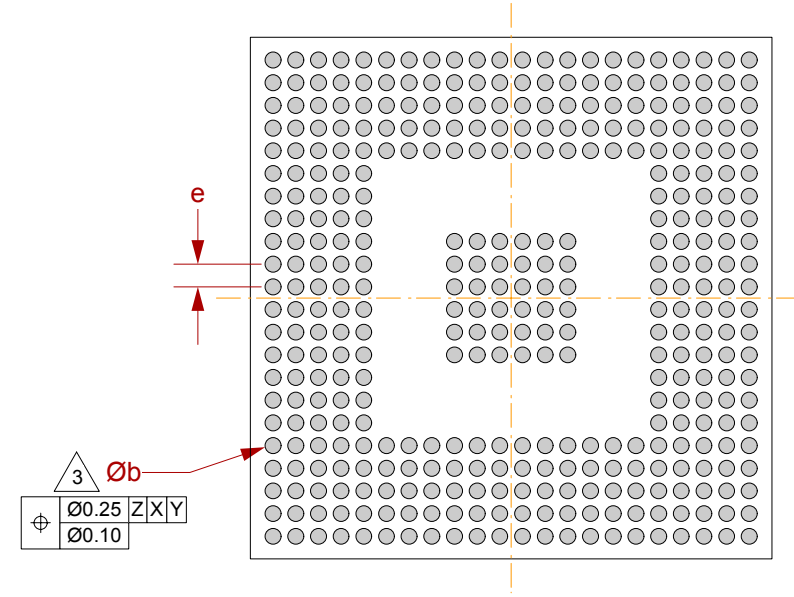


TOP VIEW

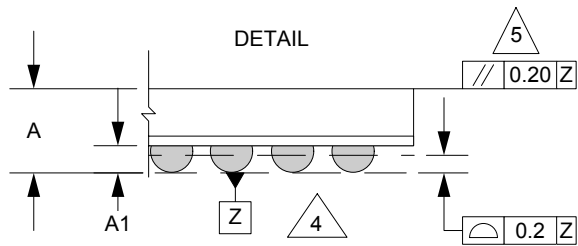


SIDE VIEW

Solder balls will be removed




BOTTOM VIEW



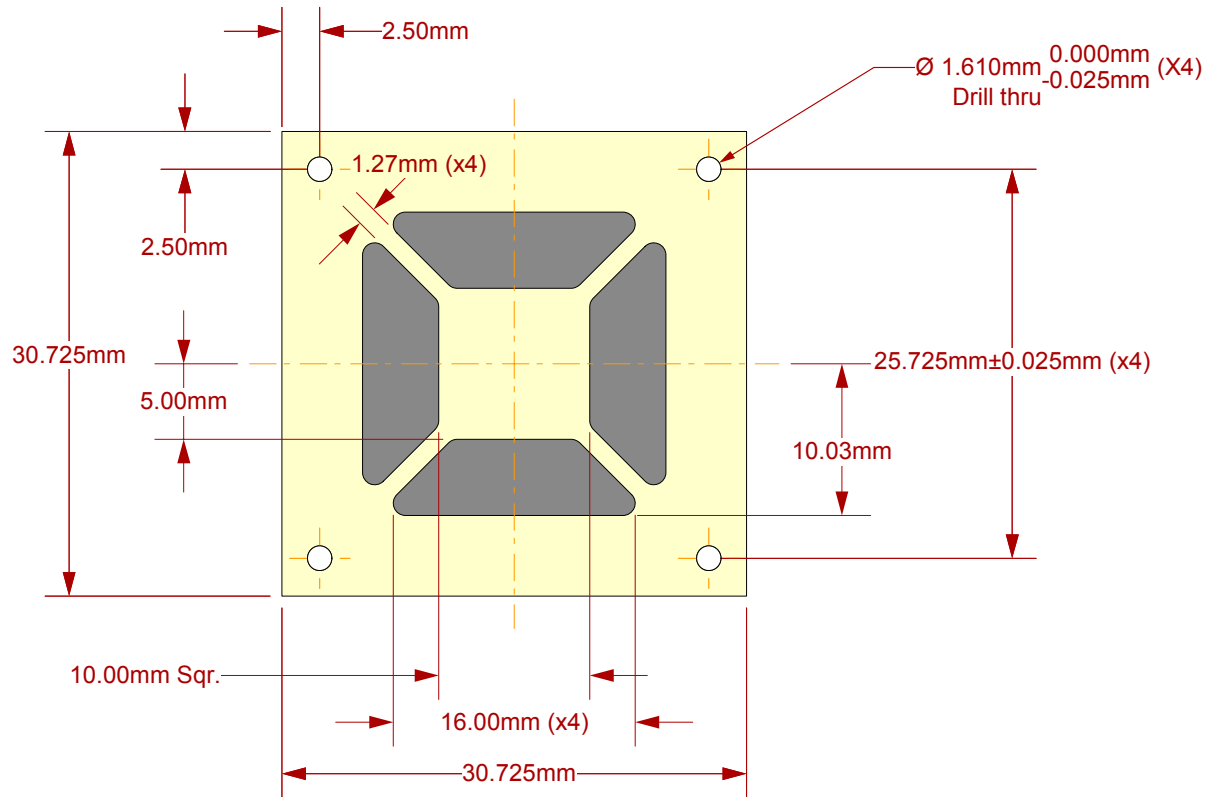
1. Dimensions are in millimeters.
  2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- △3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
  - △4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
  - △5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.45
A1	0.4	0.6
b		0.7
D	23.00 BSC	
E	23.00 BSC	
e	1.0 BSC	

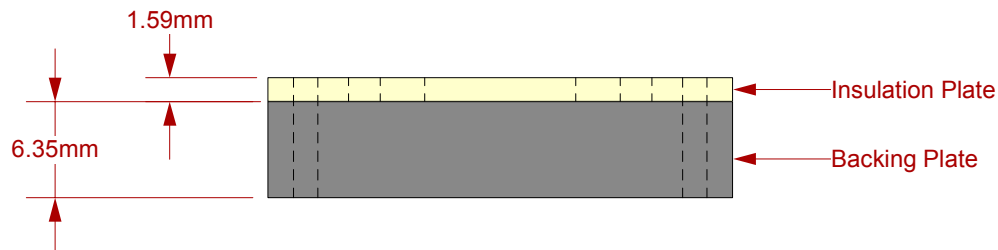
22x22 Array

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	Drawing: H. Hansen	Date: 2/1/06		
	File: SS-LGA376A-01 Dwg	Modified:		

Top View




Side View

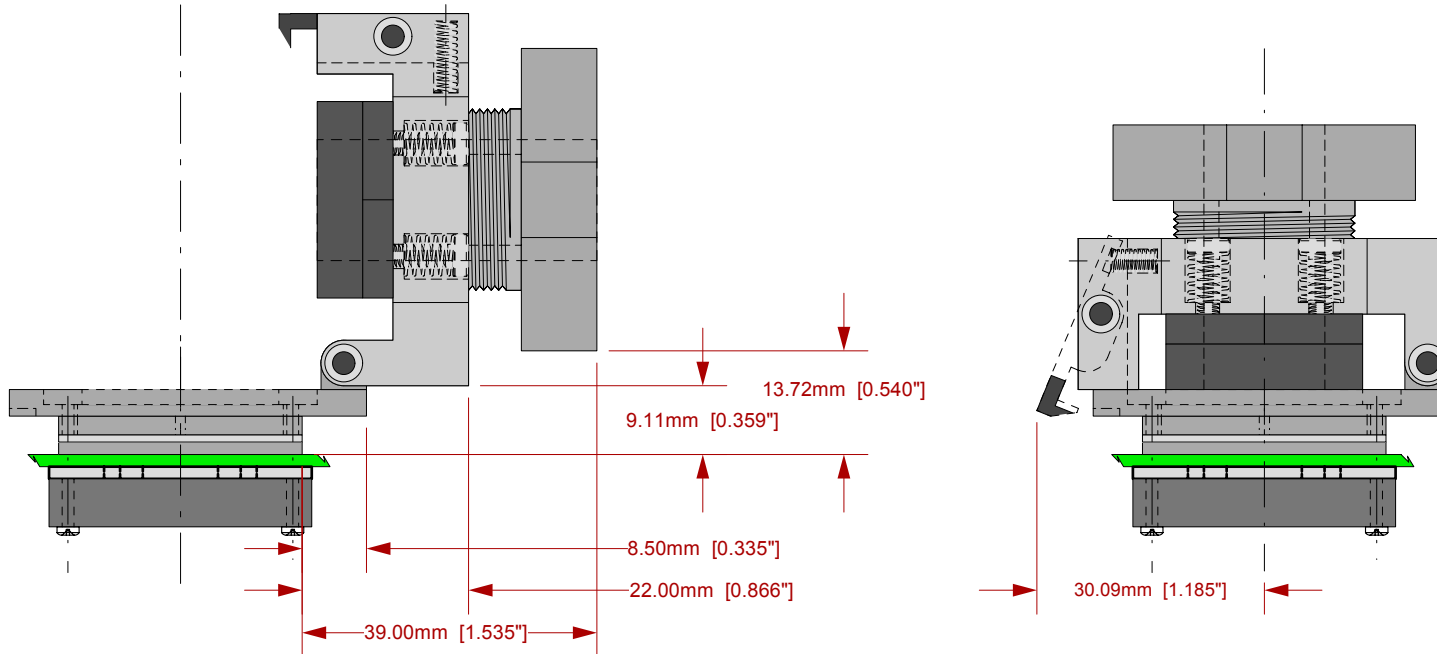
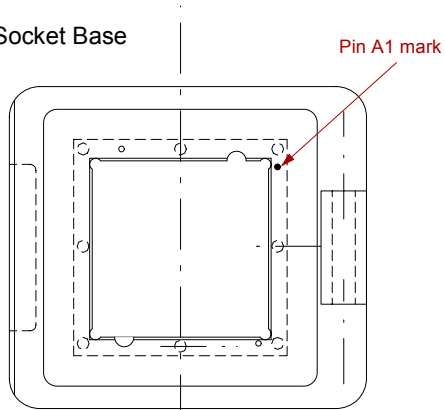



Description: Backing Plate with Insulation Plate

All dimensions are in mm.  
All tolerances are +/- 0.125mm.  
(Unless stated otherwise)

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		Drawing: H. Hansen		Date: 2/1/06
		File: SS-LGA376A-01 Dwg		Modified:

Top View of Socket Base



	<b>SS-LGA376A-01 Drawing</b>	Status: Released	Scale: 1.25:1	Rev: A
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		File: SS-LGA376A-01 Dwg		Modified:

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.